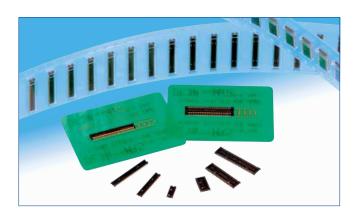
0.4mm Pitch, 0.9mm Height, Board-to-Board / Board-to-FPC Connectors

DF30 Series



Space-saving design Connector footprint is minimized. <40 contacts, mated> (0.90)Fig.1

Features

1. High-density mounting

This connector offers a space-saving design that reduces the connector footprint.

The low stacking height of 0.9mm is highly suited for applications that require a low mounted height. (Fig.1)

2. High contact reliability

Projections on the header terminals increase the wiping ability and provide superior mating reliability. During mating, the projections of the header terminals produce a tactile click, which helps to confirm proper insertion. (Fig.2)

3. Self-alignment feature

A self-alignment range of 0.3mm is provided on the receptacle and allows for easier mating in tight spaces. (Fig.3)

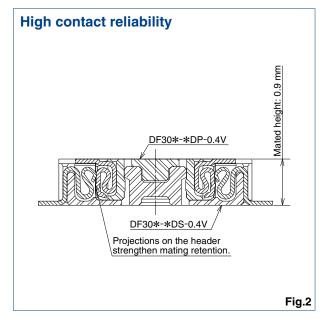
4. Wide selection of pin counts

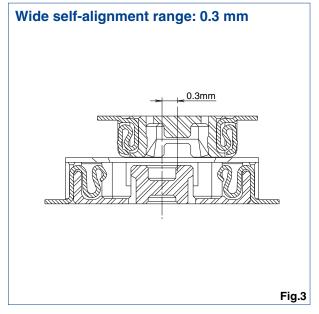
Standard pin counts are 20, 22, 24, 30, 34, 40, 50, 60, 70, and 80 positions. Smaller pin counts are also available that are applicable to LCD and camera modules in cell phones.

5. Suitable for automatic mounting

Although this connector is extremely small, it still has a sufficient vacuum area for pick-and-place machines to hold the part.

Receptacle area: 1.12mm Header area: 1.11mm





■Product Specifications

Rating	Rated curr	ent 0.3A	0.3A Operating temperature range :-35°C to 85°C (Note 1) Storage temperature		Storage temperature range	-10°C to 60°C (Note 2)	
Hatting	Rated volta	age 30V AC	Operating humidity range	: Relative humidity 20%	% to 80% Storage humidity range Relative humidity		Relative humidity 40% to 70% (Note 2)
Item	1	Specification		Conditions			
1. Insulation re	esistance	50MΩ min.	•		100V	/ DC	
2. Withstandin	ng voltage	No flashov	er or insulation break	kdown.	100V	AC / 1 minute	
3. Contact res	sistance	100mΩ ma	ix.		100 r	mA	
4. Vibration No electrical discontinuity		al discontinuity of 1μ	ι of 1 μs or more		Frequency: 10 to 55 Hz, single amplitude of		
		0.7			0.75mm, 2 hours, 3 axis		
5. Humidity		Contact resistance : 100mΩ max.			96 hours at temperature of 40℃±2℃ and RH of		
3. Humany	Insulation resistance : 25MΩ min.		in.	90% to 95%			
		Contact resistance : 100mΩ max.		Temperature: $-55^{\circ}C \rightarrow +5^{\circ}C$ to $+35^{\circ}C \rightarrow +85^{\circ}C \rightarrow +5^{\circ}C$ to $+35^{\circ}C$			
6. Temperatur	re cycle	Insulation resistance : 50MΩ min.		Duration : 30→10→30→10(Minutes)			
			Thousand Food and Contact Times		5 cycles		
7. Durability (insertions/w	vithdrawals)	Contact resistance : 100 m Ω max.		ax.	50 cycles		
8. Resistance	to	No deform	ation of components	affecting	Reflow : At the recommended temperature profile		
soldering he	eat	performance.		_	Manual soldering: 350℃ for 3 seconds		

Note 1: Includes temperature rise caused by current flow.

Note 2: The term "storage" refers to products stored for long period of time prior to mounting and use. Operating temperature range and humidity range covers non-conducting condition of installed connectors in storage, shipment or during transportation.

■ Materials

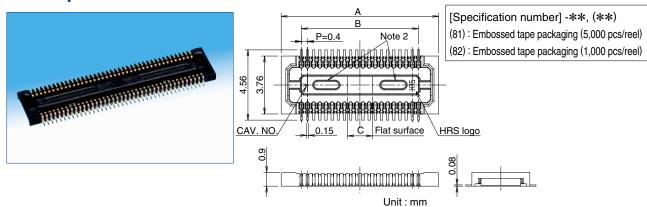
Connectors	Component	Material	Finish	Remarks
Receptacles and	Insulator	LCP	Color : Black	UL94V-0
Headers	Contacts	Phosphor bronze	Gold plated	

■Product Number Structure

Receptacles and Headers

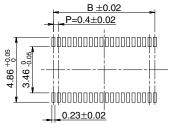
①Series name: DF30	5Contact pitch : 0.4mm
2Configuration	6 Termination section
FC/RC: Without metal fittings, without bosses	V : Straight SMT
3 Number of contacts : 20, 22, 24, 30, 34, 40, 50, 60, 70, 80	Packaging
4Connector type	(81): Embossed tape packaging (5,000 pcs/reel)
DS : Double row receptacle	(82): Embossed tape packaging (1,000 pcs/reel)
DP : Double row header	

■Receptacles



Part No.	HRS No.	No. of contacts	Α	В	С	RoHS
DF30FC-20DS-0.4V(**)	684-1109-8 **	20	6.22	3.6		
DF30FC-22DS-0.4V(**)	684-1110-7 **	22	6.62	4.0	1.2	
DF30FC-24DS-0.4V(**)	684-1111-0 **	24	7.02	4.4	1.2	
DF30FC-30DS-0.4V(**)	684-1112-2 **	30	8.22	5.6		
DF30FC-34DS-0.4V(**)	684-1113-5 **	34	9.02	6.4	1.36	Yes
DF30FC-40DS-0.4V(**)	684-1078-6 **	40	10.22	7.6	1.6	res
DF30FC-50DS-0.4V(**)	684-1114-8 **	50	12.22	9.6	2.0	
DF30FC-60DS-0.4V(**)	684-1082-3 **	60	14.22	11.6	2.4	
DF30FC-70DS-0.4V(**)	684-1115-0 **	70	16.22	13.6	2.8	
DF30FC-80DS-0.4V(**)	684-1116-3 **	80	18.22	15.6	3.2	

◆ Recommended PCB mounting pattern

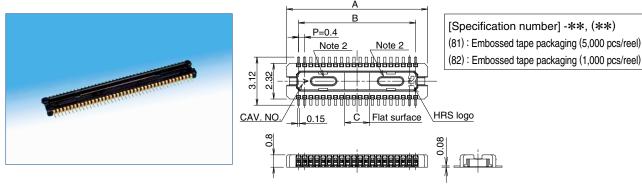


Recommended solder paste thickness: 120 μ m

Note 1: Order by number of reels.

Note 2: Receptacles with 24 or fewer contacts positions will not have recessed areas.

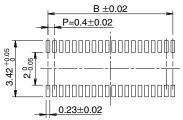
■ Header



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Part No.	HRS No.	No. of contacts	Α	В	С	RoHS
DF30RC-20DP-0.4V(**)	684-1268-1 **	20	5.14	3.6		
DF30RC-22DP-0.4V(**)	684-1269-4 **	22	5.54	4.0	1.2	
DF30RC-24DP-0.4V(**)	684-1270-3 **	24	5.94	4.4	1.2	
DF30RC-30DP-0.4V(**)	684-1271-6 **	30	7.14	5.6		
DF30RC-34DP-0.4V(**)	684-1272-9 **	34	7.94	6.4	1.36	Yes
DF30RC-40DP-0.4V(**)	684-1273-1 **	40	9.14	7.6	1.6	res
DF30RC-50DP-0.4V(**)	684-1275-7 **	50	11.14	9.6	2.0	
DF30RC-60DP-0.4V(**)	684-1276-0 **	60	13.14	11.6	2.4	
DF30FC-70DP-0.4V(**)	684-1077-3 **	70	15.14	13.6	2.8	
DF30FC-80DP-0.4V(**)	684-1144-9 **	80	17.14	15.6	3.2	

Recommended PCB mounting pattern



Recommended solder paste thickness: 120 $\mu \mathrm{m}$

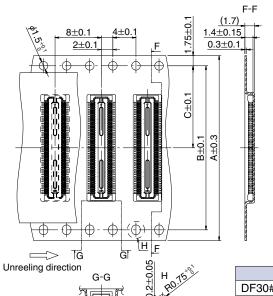
Note 1: Order by number of reels.

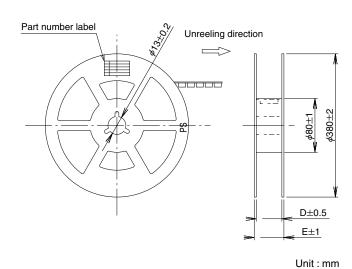
Note 2: Receptacles with 24 or fewer contacts positions will not have recessed areas.

▶ Packaging Specification

● Embossed Carrier Tape Dimensions - Receptacle

Reel Dimensions



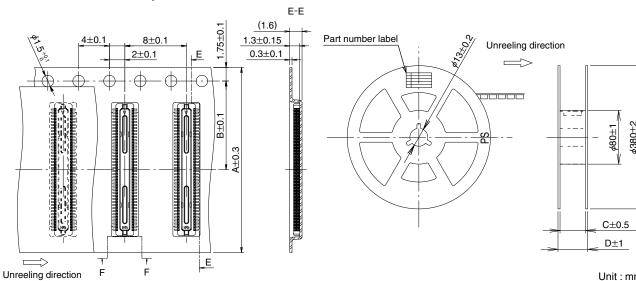


Part No.	Α	В	С	D	Е
DF30#-20DS-0.4V(**)					
DF30#-22DS-0.4V(**)	16.0		7.5	7.5 17.5	5 21.5
DF30#-24DS-0.4V(**)					
DF30#-30DS-0.4V(**)					
DF30#-34DS-0.4V(**)		_			
DF30#-40DS-0.4V(**)					
DF30#-50DS-0.4V(**)	04.0		115	0E E	29.5
DF30#-60DS-0.4V(**)	24.0	11.5 2	11.5 25.5	25.5	29.5
DF30#-70DS-0.4V(**)					
DF30#-80DS-0.4V(**)	32.0	28.4	14.2	33.5	37.5

Embossed tape 32mm or wider will have perforated feed holes on two sides.

● Embossed Carrier Tape Dimensions - Header

Reel Dimensions



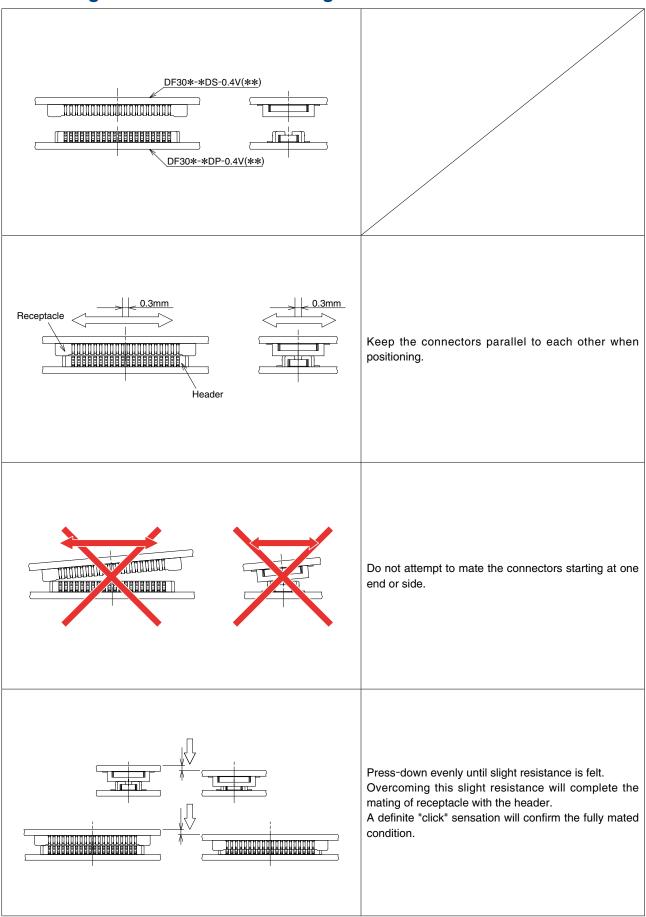
F-F	

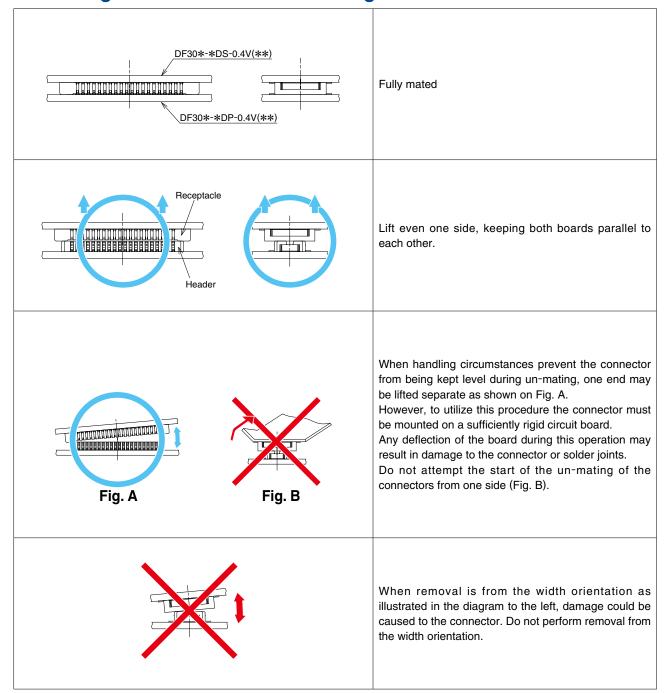
				Unit : mm
Part No.	Α	В	С	D
DF30#-20DP-0.4V(**)				
DF30#-22DP-0.4V(**)	**)			
DF30#-24DP-0.4V(**)	100	16.0 7.5 17.5	17.5	21.5
DF30#-30DP-0.4V(**)	16.0		21.5	
DF30#-34DP-0.4V(**)				
DF30#-40DP-0.4V(**)				
DF30#-50DP-0.4V(**)				
DF30#-60DP-0.4V(**)	04.0	11.5	25.5 29	00.5
DF30#-70DP-0.4V(**)	24.0	11.5		29.5
DF30#-80DP-0.4V(**)				

● Usage Recommendations

Recommended temperature	
profile	Ordinary solder cream
	220
	220
	10 to 20 sec.
	150 Soldering Soldering
	Preheating
	100/
	<u> </u>
	Time (accords)
	Time (seconds)
	Lead-free solder cream 10 seconds or less
	230
	250 230
	Soldering \ 150
	150 60 to 120 sec. Preheating
	100
	√
	Time (seconds)
	Note 1 : Up to 2 cycles of Reflow soldering are possible under the same conditions, provided that there is a
	return to normal temperature between the first and second cycle.
	Note 2 : The temperature profile indicates the board surface temperature at the point of contacts with the
2. Recommended manual soldering	connector terminals. Manual soldering : 340±10°C for 3 seconds
3. Recommended screen thickness	Thickness: 0.12mm
and open area ratio	Opening are ratio: DS side 100%, DP side 84%
(Pattern area ratio)	
4. Board warpage	Maximum of 0.02mm at the connector center, with both ends of the connector as
	reference points.
Cleaning conditions Precautions	Please refer to the "Handbook on the Use of Wire-to-Board Connectors". ■ Terminals are exposed on the header side. Please note that touching them with bare
0. Frecautions	hands causes contact failure or static electricity, resulting in damage to the components.
	■ Note that mating/unmating when the product is not mounted on the PCB could cause
	damage or deformation of the terminal.
	■ Avoid supporting the PCB using only the connectors. Other means of support are
	needed.
	■ Care should be taken that excessive prying during mating/unmating could cause
	damage.
	■ In the case of hand soldering, please do not apply any flux, which could cause flux
	wicking.
	■ The product may differ slightly in color due to different production lots of the resin. This
	color variation has no influence on the performance.
	■ Please refer to the next page for the precautions for mating/unmating.
	Care should be taken to secure the mated connector and FPC within the device with
	housings and cushioning materials. This will help prevent disconnections or unmating in
	the event of dropping, other external forces or stressed routing of the FPC.

● Handling Precautions when mating the connectors





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